

Boschman Advanced Packaging Technology achieves breakthrough in the Ag-sinter market for Electrical Vehicles.

Duiven, the Netherlands, 10 December 2018. Boschman Advanced Packaging Technology has achieved a breakthrough in the industrialized pressurized Ag-sinter market. Reaching > 40 installed systems and an estimated market share of > 75%. Recently new orders for Ag-Sinter Equipment were received from ON-Semi, Siemens, Fraunhofer IZM, Fraunhofer IISB, and Robert Bosch.



Fully automatic Ag- Sinter system: Sinterstar Inline-F-XL-HC

Frank Boschman comments: *“For the EV segment precise process control and automatic monitoring of all process parameters are key design features to help our customers go into high volume production in a controlled way. Customers can benefit from the experience and expertise built up at Boschman to capitalize on the business opportunities at hand.”*

Proprietary technology

Through their proprietary film and dynamic insert technology, Boschman was the first player on the market with the introduction of a manual industrial sinter platform (Sinterstar Innovate-F-XL) in 2014. Over the course of the following 3 years, Boschman introduced a full portfolio of fully automated machines, full set of supporting tools and in-house support and assembly.

This is all based on existing and proven technology from their film-assisted-molding transfer-molding machines, whilst continuously improving the flexibility and reliability of the sintering solutions. Boschman got noticed and recognized for their performance from the end of 2017 onwards, greatly accelerating in 2018. This resulted in the sales of multiple systems to almost all leading companies in the field of automotive power electronics.

Power modules

Next to delivering equipment (Ag-Sintering and FAM Molding) Boschman is also active in package development for power modules. Several large customers have partnered with Boschman to develop state-of-the-art power module packages and provide prototypes.

Note for the press:

About Boschman Advanced Packaging Technology

Boschman Advanced Packaging Technology in Duiven Netherlands established in 1987 is a high-end niche player within the semiconductor packaging equipment sector. They provide full production solutions for semiconductor packaging specifically in transfer-molding and silver sintering die-attach, including package development and assembly services.

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